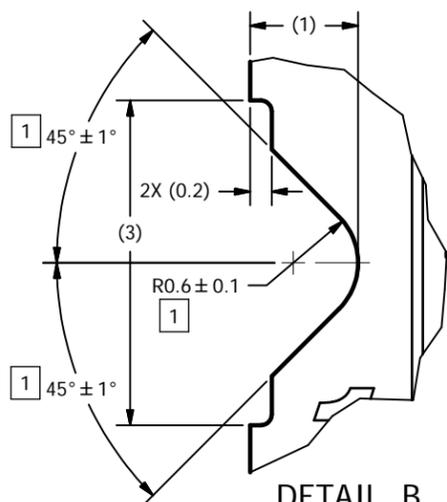
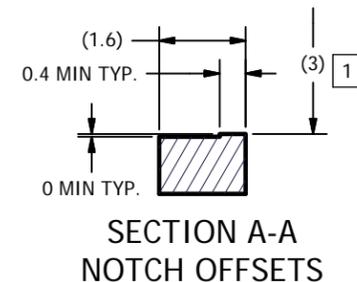
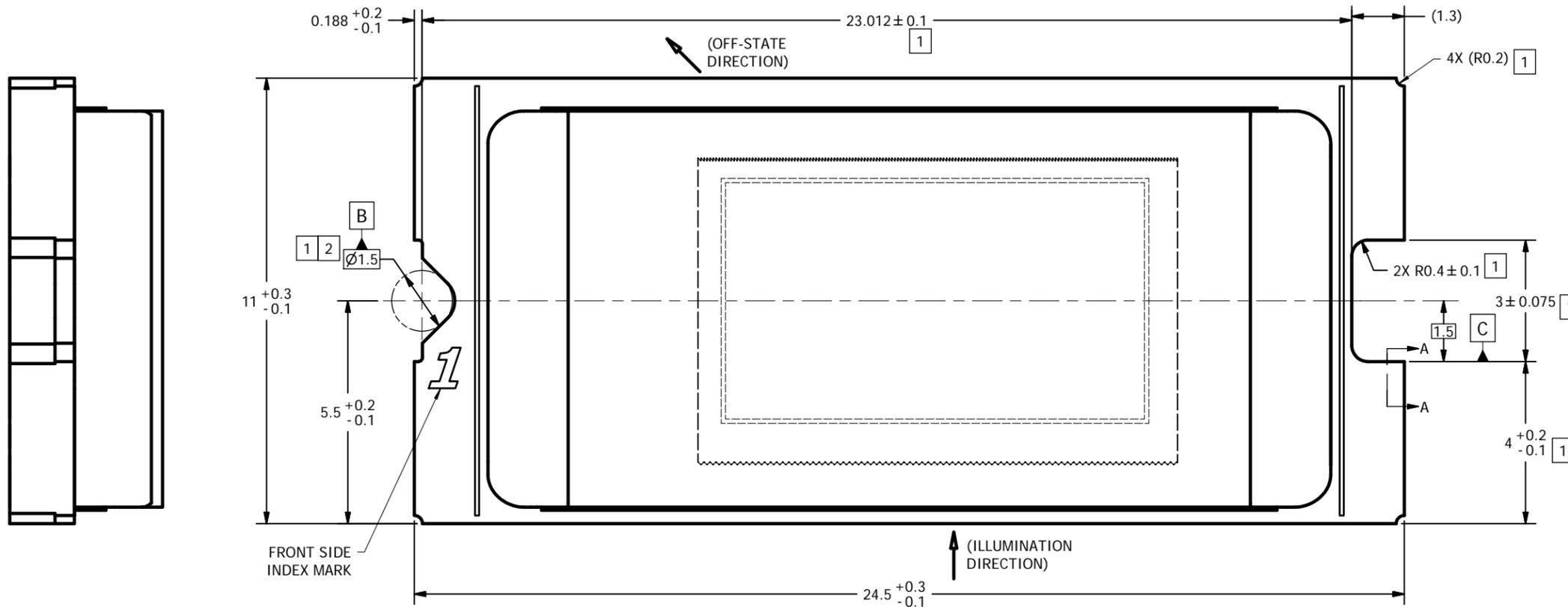


NOTES UNLESS OTHERWISE SPECIFIED:

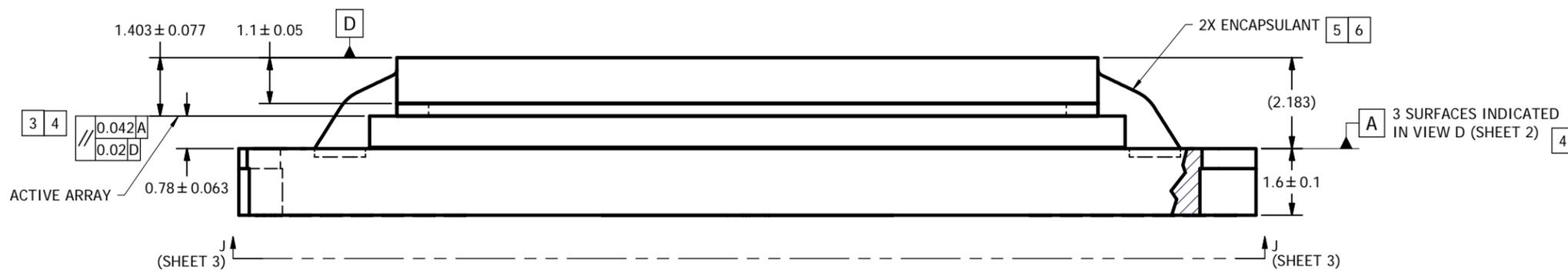
- 1 NOTCH DIMENSIONS ARE DEFINED BY UPPERMOST LAYERS OF CERAMIC, AS SHOWN IN SECTION A-A.
- 2 SEE DETAIL B FOR "V-NOTCH" DIMENSIONS.
- 3 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
- 4 WHILE ONLY THE THREE DATUM A TARGET AREAS A1, A2, AND A3 ARE USED FOR MEASUREMENT, ALL 4 CORNERS SHOULD BE CONTACTED, INCLUDING E1, TO SUPPORT MECHANICAL LOADS.
- 5 ENCAPSULANT TO BE CONTAINED WITHIN DIMENSIONS SHOWN IN VIEW D (SHEET 2). NO ENCAPSULANT IS ALLOWED ON TOP OF THE WINDOW.
- 6 ENCAPSULANT NOT TO EXCEED THE HEIGHT OF THE WINDOW.
- 7 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.6 DEGREES.
- 8 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE ARRAY.

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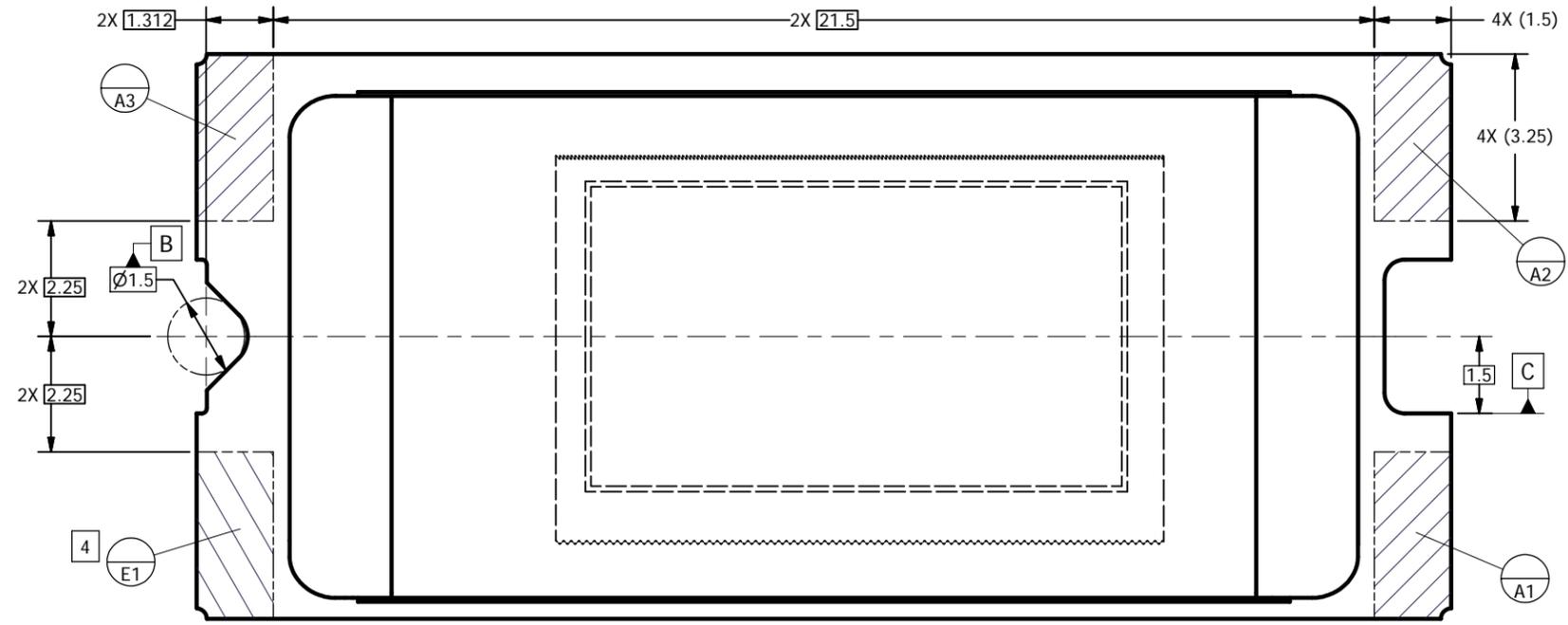
REVISIONS			
REV	DESCRIPTION	DATE	BY
A	ECO 2140050: INITIAL RELEASE	2/20/2014	BMH
B	ECO 2140429: CORRECT DATUM C IN VIEW J-J, SH. 3	3/6/2014	BMH
C	ECO 2142093: DELETE BACK SIDE FLATNESS SPEC	5/22/2014	BMH
D	ECO 2145057: ADD "FOL PACKAGE" TO DRAWING TITLE	7/20/2016	BMH



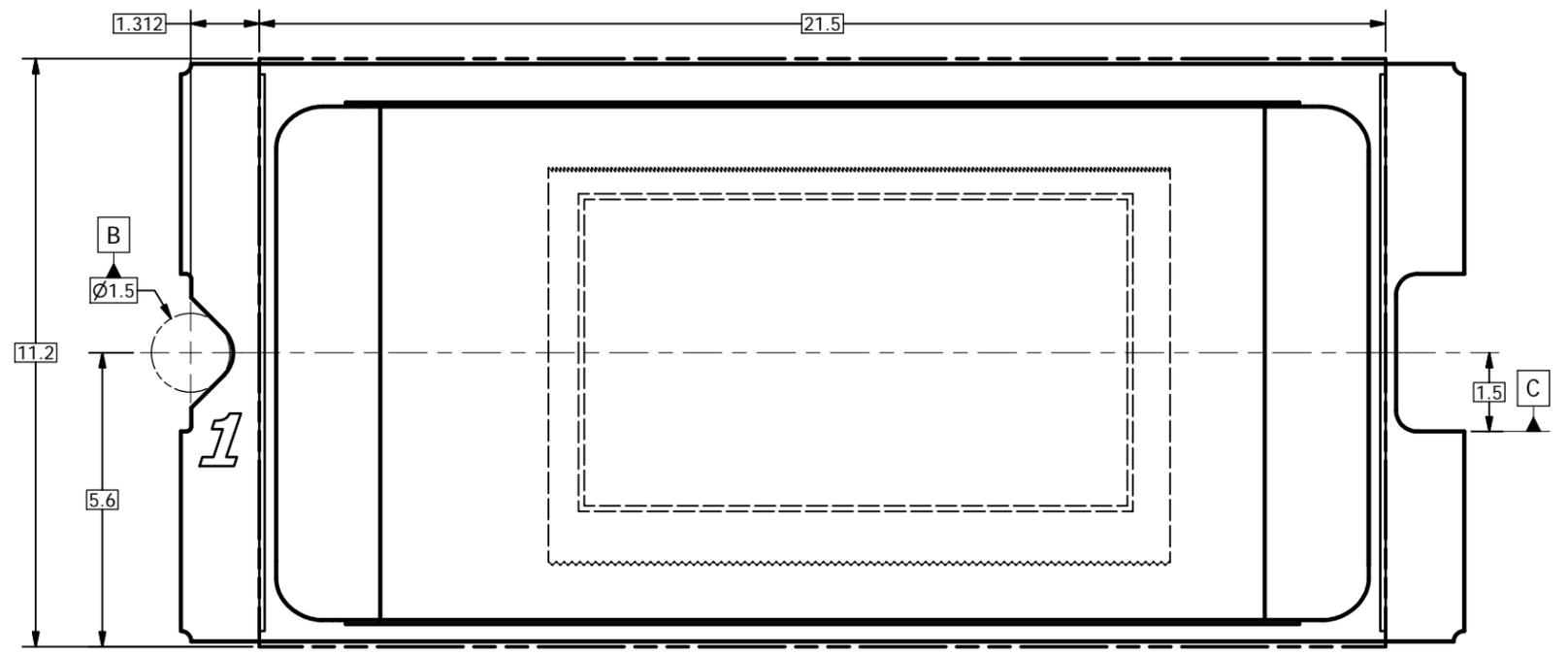
DETAIL B
V-NOTCH
SCALE 30 : 1



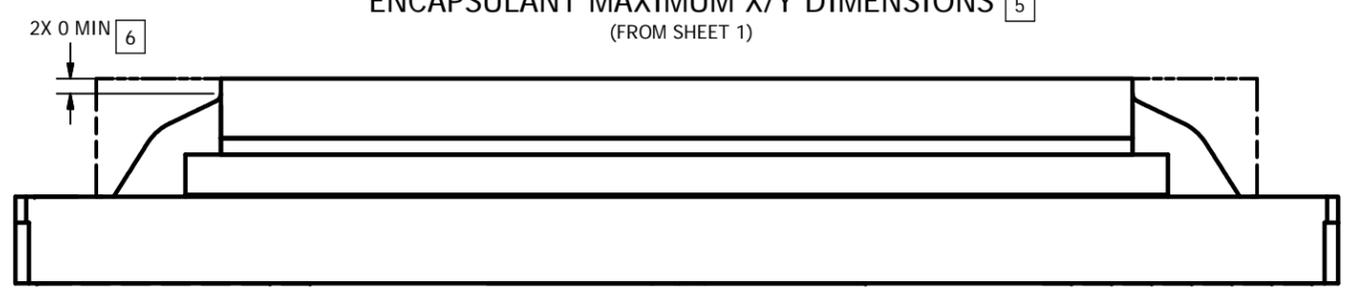
UNLESS OTHERWISE SPECIFIED ● DIMENSIONS ARE IN MILLIMETERS ● TOLERANCES: ANGLES ± 1° 2 PLACE DECIMALS ± 0.25 1 PLACE DECIMALS ± 0.50 ● DIMENSIONAL LIMITS APPLY BEFORE PROCEEDING ● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994 ● REMOVE ALL BURRS AND SHARP EDGES ● PARENTHETICAL INFORMATION FOR REFERENCE ONLY	DRAWN B. HASKETT ENGINEER B. HASKETT QA/CE P. KONRAD CM S. SUSI M. DORAK APPROVED R. LONG	DATE 2/20/2014 2/20/2014 2/26/2014 2/25/2014 2/23/2014 2/26/2014	TEXAS INSTRUMENTS Dallas, Texas TITLE ICD, MECHANICAL, DMD, .47 1080p SERIES 312 (FOL PACKAGE)	
	APPLICATION 0314DA NEXT ASSY USED ON	SIZE D		DWG NO. 2513652
	SCALE 15:1	SHEET 1 OF 3		REV D
	INVT11-2006a			



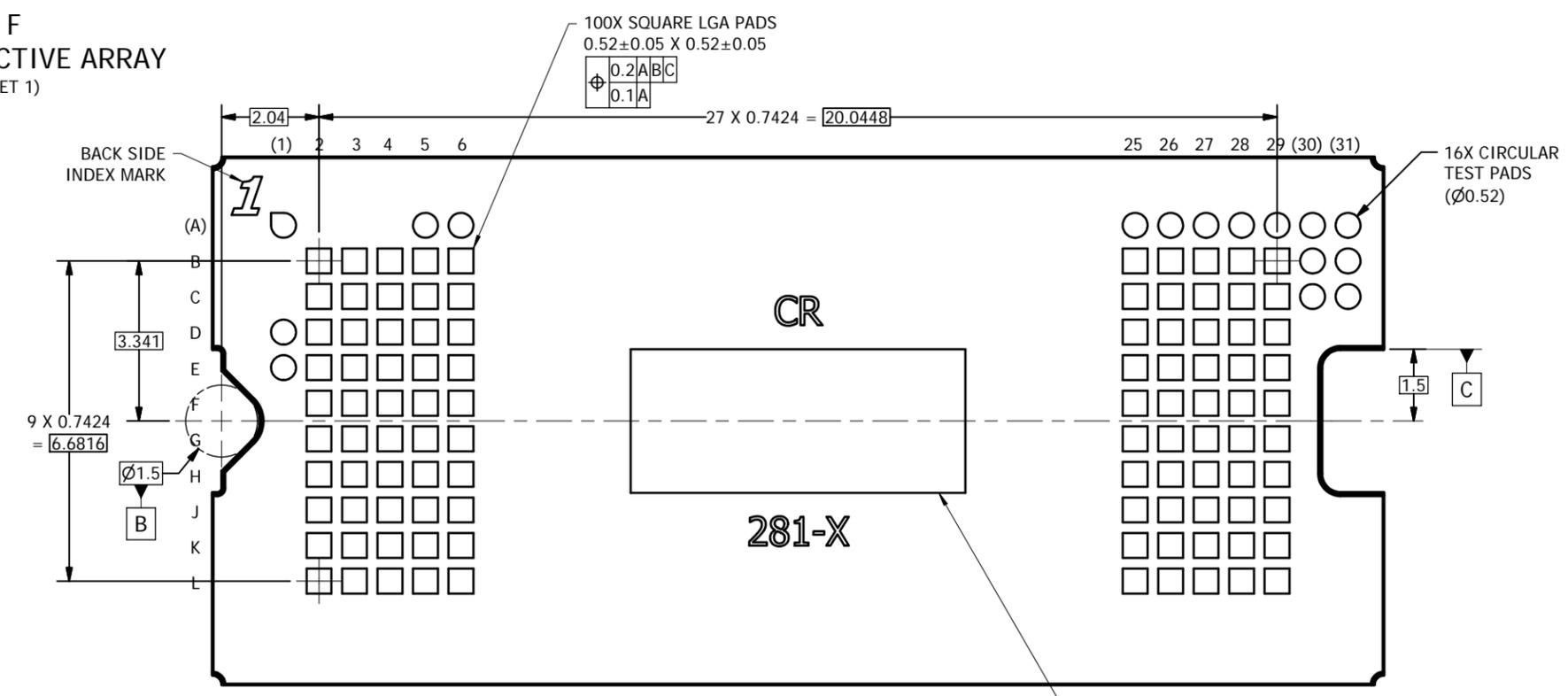
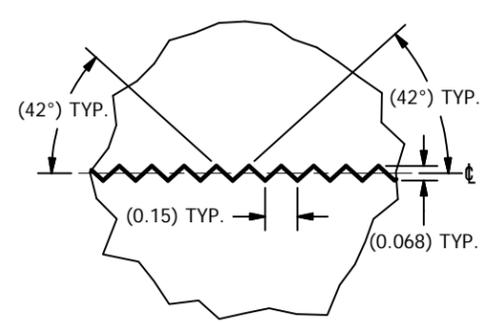
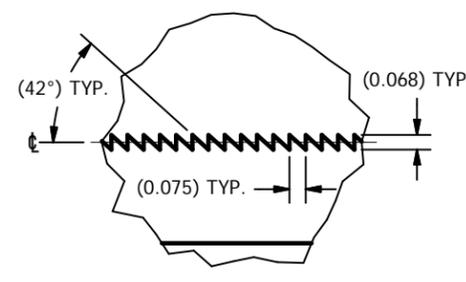
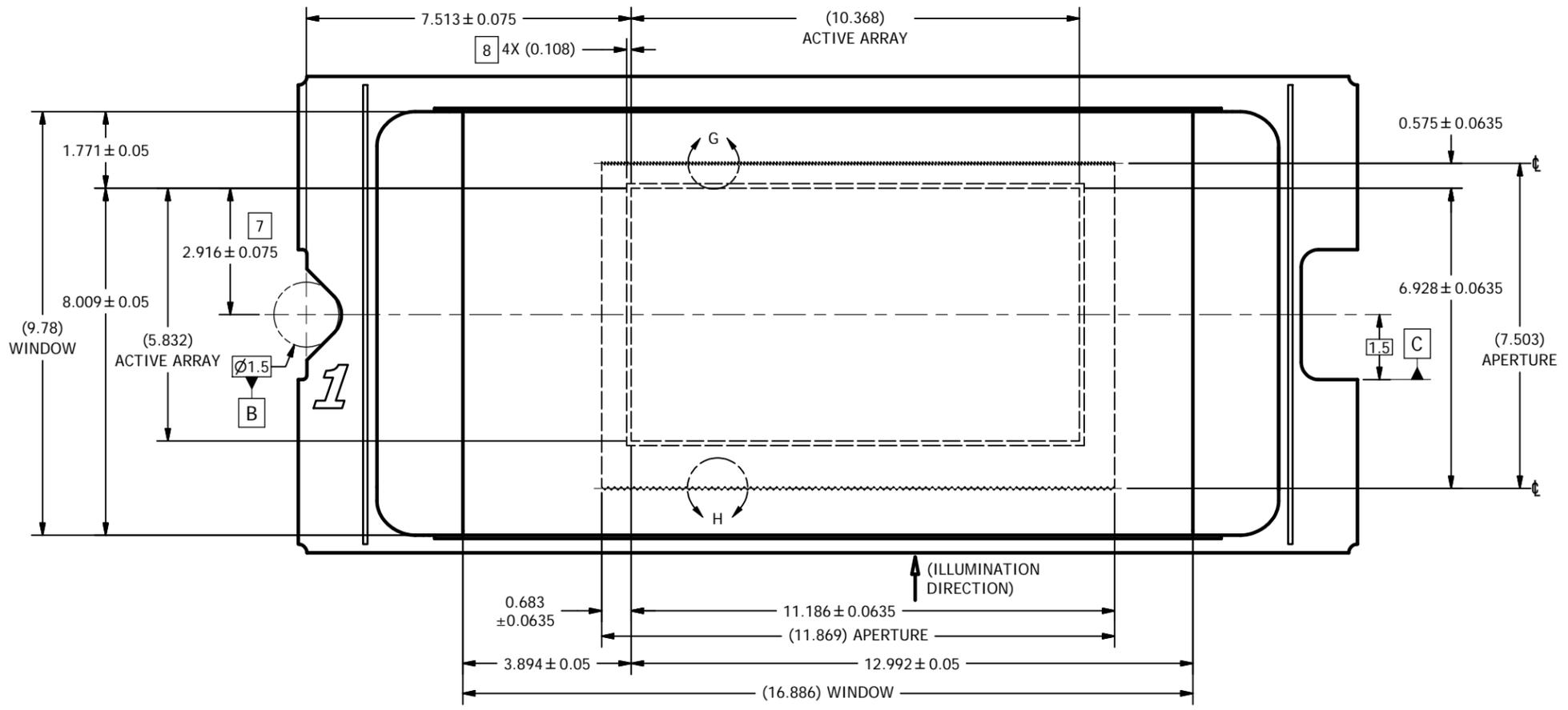
VIEW C
DATUMS A AND E
(SUBSTRATE METALLIZATION OMITTED FOR CLARITY)
(FROM SHEET 1)



VIEW D
ENCAPSULANT MAXIMUM X/Y DIMENSIONS 5
(FROM SHEET 1)



VIEW E
ENCAPSULANT MAXIMUM HEIGHT



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